

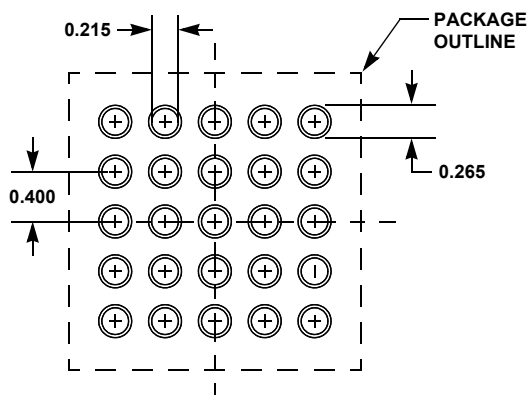
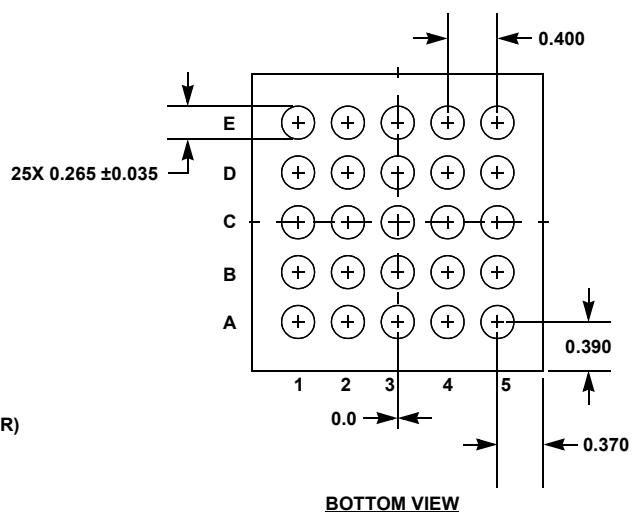
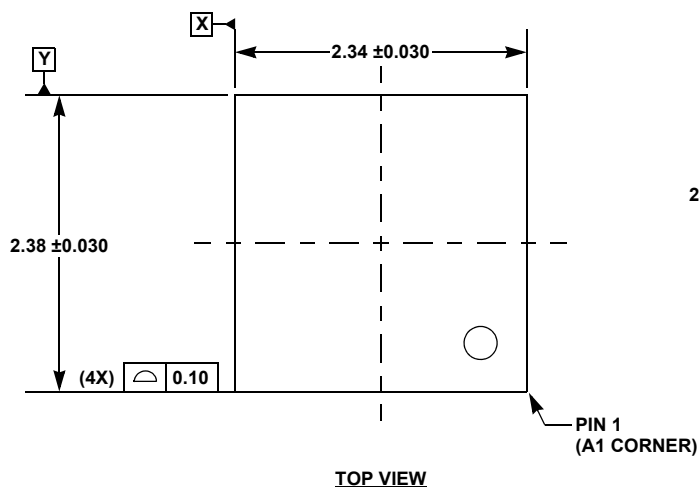
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

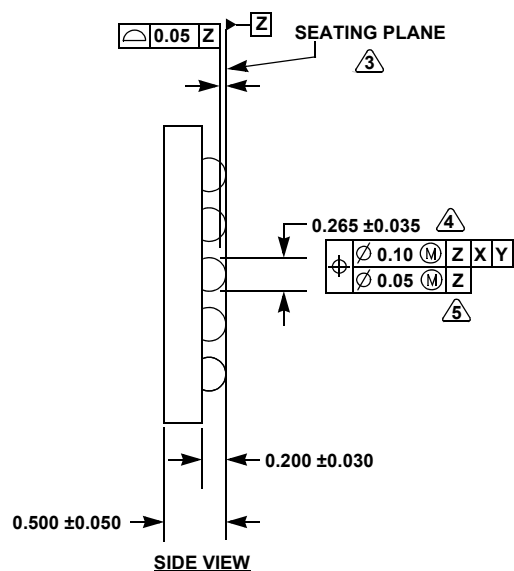
### W5x5.25G

5x5 ARRAY 25 BALLS WITH 0.4mm PITCH WAFER LEVEL CHIP SCALE PACKAGE (WLCSP)

Rev 0, 12/16



6. NSMD



#### NOTES:

- All dimensions are in millimeters.
- Dimensions and tolerance per ASME Y14.5M - 1994.
- Primary datum  $Z$  and seating plane are defined by the spherical crowns of the bump.
- Dimension is measured at the maximum bump diameter parallel to primary datum  $Z$ .
- Bump position designation per JESD 95-1, SPP-010.
- NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).